

## PART ONE: General description

<input type="text"/>	<input type="text"/>	07/12/00
<i>Process name</i>	<i>Process Code</i>	<i>Last Update</i>
<input type="text" value="Terry Mason"/>	<input type="text"/>	
<i>Author</i>	<i>Contact Information (Email)</i>	
<input type="text" value="Circuit board recipe"/>		
<i>General description of process</i>		

## PART TWO: Details

*Cleaning*

<input checked="" type="checkbox"/> ISO	<input type="text"/>	<input checked="" type="checkbox"/> Acetone	<input type="text"/>
	<i>Time (min)</i>		<i>Time (min)</i>

Singe PCB at 90° for 20 sec.

*Resist Coating*

<input type="checkbox"/> P-10	<input type="text"/>	<input type="text"/>	<input type="text"/>	<input type="text"/>
<i>Primer</i>	<i>Speed1 (RPM)</i>	<i>Time(sec)</i>	<i>Speed2 (RPM)</i>	<i>Time(sec)</i>
<input type="checkbox"/> HMDS				
<input checked="" type="checkbox"/> AZ 1512	<input type="text" value="1800"/>	<input type="text" value="40"/>	<input type="text"/>	<input type="text"/>
<i>Resist</i>	<i>Speed1 (RPM)</i>	<i>Time(sec)</i>	<i>Speed2 (RPM)</i>	<i>Time(sec)</i>
<input checked="" type="checkbox"/> PreBake	<input type="text" value="Hot Plate"/>	<input type="text" value="90"/>	<input type="text" value="40"/>	
		<i>T (°C)</i>	<i>Time(min)</i>	
<input checked="" type="checkbox"/> Exposure	<input aligner"="" type="text" value="3"/>		<input type="text"/>	
			<i>Time(sec)</i>	
<input checked="" type="checkbox"/> Develope	<input type="text" value="AZ300"/>		<input type="text" value="40"/>	
	<i>Developer</i>		<i>Time(sec)</i>	
<input checked="" type="checkbox"/> PostBake	<input type="text" value="Hot Plate"/>	<input type="text" value="90"/>	<input type="text" value="40"/>	
		<i>T (°C)</i>	<i>Time(min)</i>	

*Etching*

PCB etchant

*etchant*

*P (PSI)*

*T (°C)*

*Time(min)*

1. Agitate PCB in PCB etchant (ferric chloride) until unwanted copper is totally removed. Due to differences in copper hardness and thickness per PCB side, etching of one side will proceed faster than the second. Periodically check both sides for etching advancement. Once a side is complete, passivate that side using packing tape to prevent unwanted under-cutting
2. Remove the tape once the etching is complete and scrub both sides of PCB with Acetone to remove photoresist
3. Rinse with DI water and dry

*comments*

*Rinse and Dry*

**PART THREE: General Comments**

Post-bake at 90? for:

- a. 20 sec. if second side process is needed
- b. 40 sec. if photo processing is complete and ready for etching